OM SENI

# AOD538

## 30V N-Channel αMOS™

### General Description

- Trench Power AlphaMOS (αMOS™ LV) technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

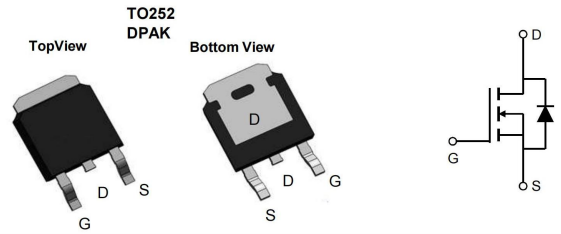
### Application

- DC/DC Converters in Computing, Servers, and POL
- Isolated DC/DC Converters in Telecom and Industrial

### Product Summary

| | |
|---|---|
| $V_{DS}$ | 30V |
| $I_D$ (at $V_{GS}$=10V) | 70A |
| $R_{DS(ON)}$ (at $V_{GS}$=10V) | < 3.1mΩ |
| $R_{DS(ON)}$ (at $V_{GS}$=4.5V) | < 4.8mΩ |

100% UIS Tested
100% Rg Tested




| Orderable Part Number | Package Type | Form | Minimum Order Quantity |
|---|---|---|---|
| AOD538 | TO-252 | Tape & Reel | 2500 |
| | | | |

**Absolute Maximum Ratings $T_A$=25°C unless otherwise noted**

| Parameter | | Symbol | Maximum | Units |
|---|---|---|---|---|
| Drain-Source Voltage | | $V_{DS}$ | 30 | V |
| Gate-Source Voltage | | $V_{GS}$ | ±20 | V |
| Continuous Drain Current [G] | $T_C$=25°C | $I_D$ | 70 | A |
| | $T_C$=100°C | | 54 | |
| Pulsed Drain Current [C] | | $I_{DM}$ | 280 | |
| Continuous Drain Current | $T_A$=25°C | $I_{DSM}$ | 34 | A |
| | $T_A$=70°C | | 27 | |
| Avalanche Current [C] | | $I_{AS}$ | 36 | A |
| Avalanche energy | L=0.1mH [C] | $E_{AS}$ | 65 | mJ |
| $V_{DS}$ Spike | 10µs | $V_{SPIKE}$ | 36 | V |
| Power Dissipation [B] | $T_C$=25°C | $P_D$ | 93 | W |
| | $T_C$=100°C | | 46 | |
| Power Dissipation [A] | $T_A$=25°C | $P_{DSM}$ | 6.2 | W |
| | $T_A$=70°C | | 4 | |
| Junction and Storage Temperature Range | | $T_J$, $T_{STG}$ | -55 to 175 | °C |

**Thermal Characteristics**

| Parameter | | Symbol | Typ | Max | Units |
|---|---|---|---|---|---|
| Maximum Junction-to-Ambient [A] | t ≤ 10s | $R_{\theta JA}$ | 15 | 20 | °C/W |
| Maximum Junction-to-Ambient [A D] | Steady-State | | 40 | 50 | °C/W |
| Maximum Junction-to-Case | Steady-State | $R_{\theta JC}$ | 1.3 | 1.6 | °C/W |

# OM SENI

**Electrical Characteristics ($T_J$=25°C unless otherwise noted)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| **STATIC PARAMETERS** | | | | | | |
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | ID=250µA, VGS=0V | 30 | | | V |
| $I_{DSS}$ | Zero Gate Voltage Drain Current | $V_{DS}$=30V, $V_{GS}$=0V | | | 1 | µA |
| | | $T_J$=55°C | | | 5 | |
| $I_{GSS}$ | Gate-Body leakage current | $V_{DS}$=0V, $V_{GS}$=±20V | | | ±100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}$=$V_{GS}$, $I_D$=250µA | 1.4 | 1.8 | 2.2 | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}$=10V, $I_D$=20A | | 2.5 | 3.1 | mΩ |
| | | $T_J$=125°C | | 3.6 | 4.5 | |
| | | $V_{GS}$=4.5V, $I_D$=20A | | 3.8 | 4.8 | mΩ |
| $g_{FS}$ | Forward Transconductance | $V_{DS}$=5V, $I_D$=20A | | 91 | | S |
| $V_{SD}$ | Diode Forward Voltage | $I_S$=1A,$V_{GS}$=0V | | 0.7 | 1 | V |
| $I_S$ | Maximum Body-Diode Continuous Current [G] | | | | 70 | A |
| **DYNAMIC PARAMETERS** | | | | | | |
| $C_{iss}$ | Input Capacitance | $V_{GS}$=0V, $V_{DS}$=15V, f=1MHz | | 2160 | | pF |
| $C_{oss}$ | Output Capacitance | | | 915 | | pF |
| $C_{rss}$ | Reverse Transfer Capacitance | | | 115 | | pF |
| $R_g$ | Gate resistance | f=1MHz | 0.9 | 1.8 | 2.7 | Ω |
| **SWITCHING PARAMETERS** | | | | | | |
| $Q_g$(10V) | Total Gate Charge | $V_{GS}$=10V, $V_{DS}$=15V, $I_D$=20A | | 30 | 42 | nC |
| $Q_g$(4.5V) | Total Gate Charge | | | 14 | 20 | nC |
| $Q_{gs}$ | Gate Source Charge | | | 5.1 | | nC |
| $Q_{gd}$ | Gate Drain Charge | | | 6.3 | | nC |
| $t_{D(on)}$ | Turn-On DelayTime | $V_{GS}$=10V, $V_{DS}$=15V, $R_L$=0.75Ω, $R_{GEN}$=3Ω | | 8 | | ns |
| $t_r$ | Turn-On Rise Time | | | 4 | | ns |
| $t_{D(off)}$ | Turn-Off DelayTime | | | 29 | | ns |
| $t_f$ | Turn-Off Fall Time | | | 5.5 | | ns |
| $t_{rr}$ | Body Diode Reverse Recovery Time | $I_F$=20A, dI/dt=500A/µs | | 16.5 | | ns |
| $Q_{rr}$ | Body Diode Reverse Recovery Charge | $I_F$=20A, dI/dt=500A/µs | | 34.2 | | nC |

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in$^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A$ =25° C. The Power dissipation $P_{DSM}$ is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
B. The power dissipation $P_D$ is based on $T_{J(MAX)}$=175° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Single pulse width limited by junction temperature $T_{J(MAX)}$=175° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in$^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A$=25° C.

OM SENI

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

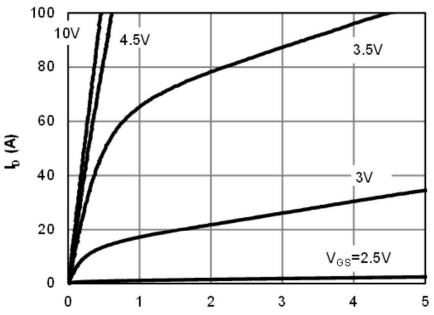



Figure 1: On-Region Characteristics (Note E)

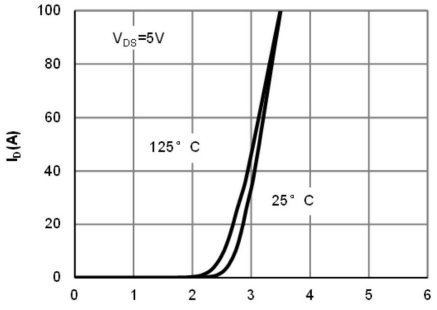



Figure 2: Transfer Characteristics (Note E)

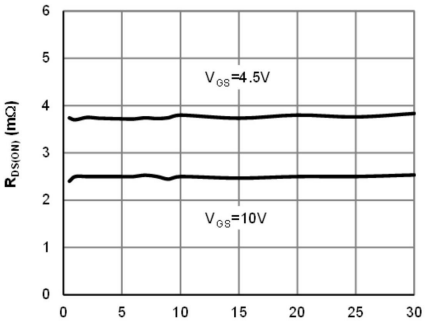



Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

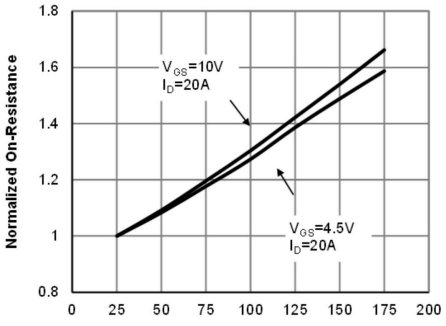



Figure 4: On-Resistance vs. Junction Temperature (Note E)

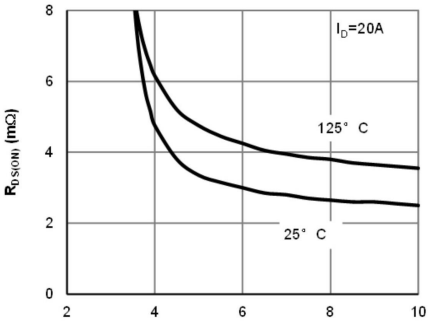



Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

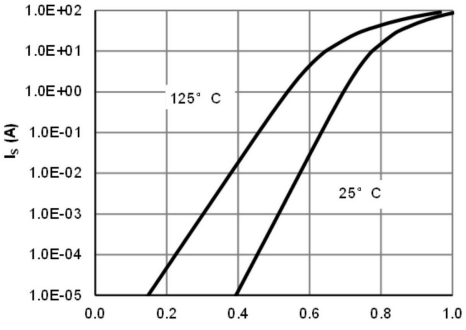



Figure 6: Body-Diode Characteristics (Note E)

# OM SENI

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

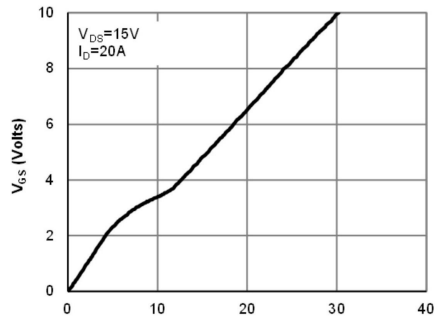



Figure 7: Gate-Charge Characteristics

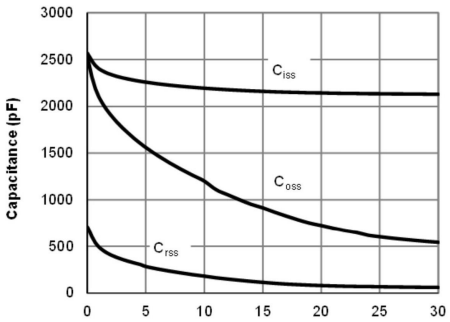



Figure 8: Capacitance Characteristics

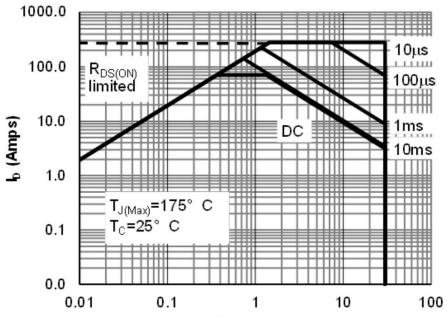



Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

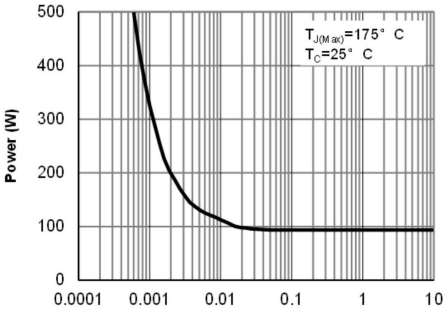



Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

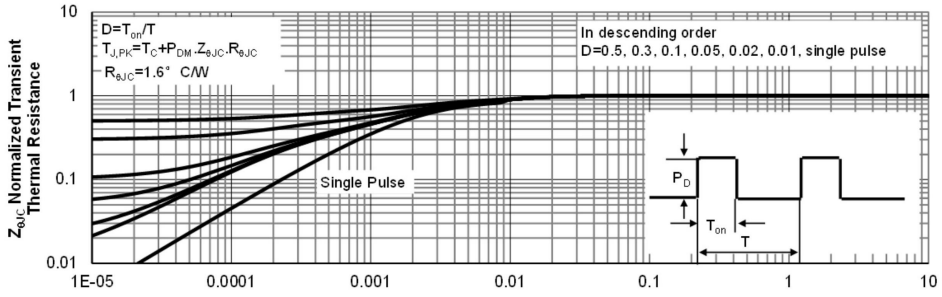



Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

# OM SENI

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

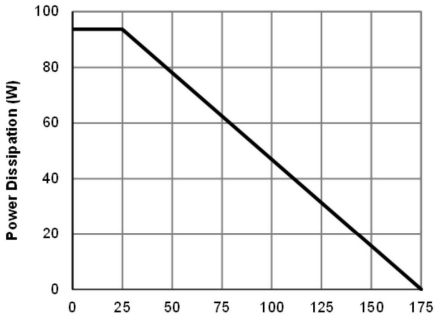



Figure 12: Power De-rating (Note F)

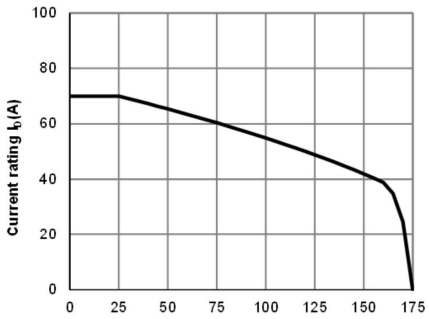



Figure 13: Current De-rating (Note F)

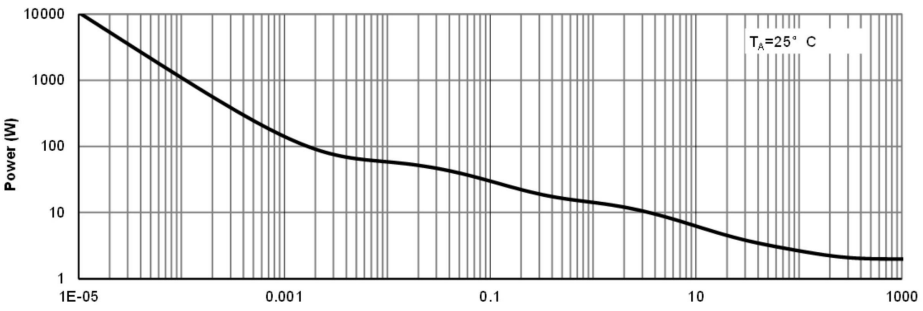



Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

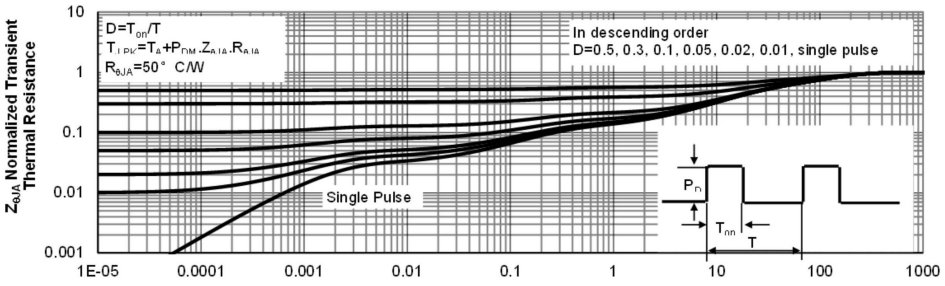
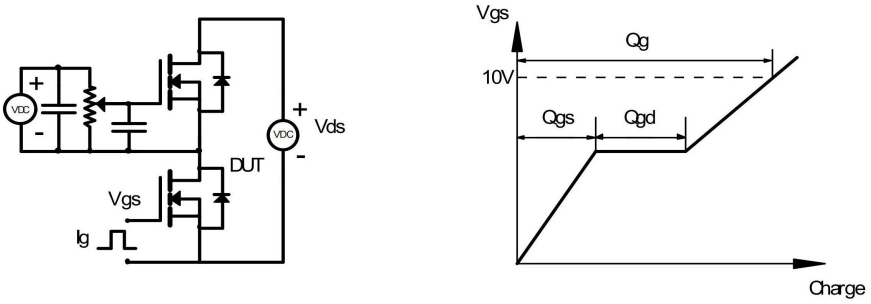


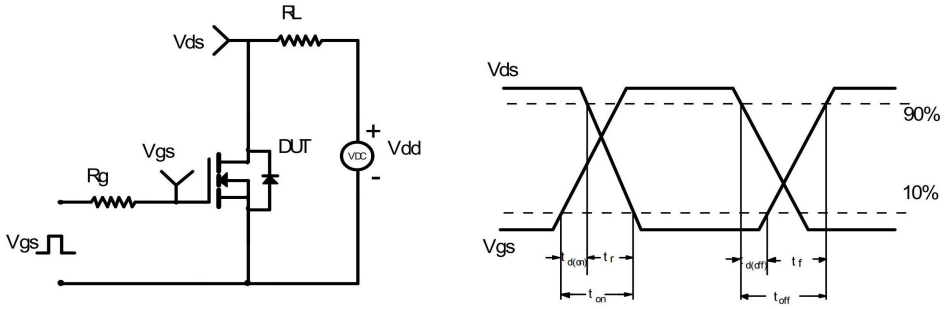

Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

# OM SENI

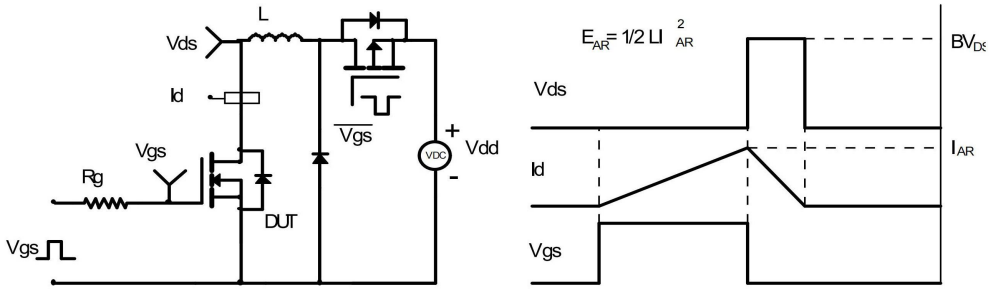
Gate Charge Test Circuit & Waveform




Resistive Switching Test Circuit & Waveforms




Unclamped Inductive Switching (UIS) Test Circuit & Waveforms




Diode Recovery Test Circuit & Waveforms

